LM108,LM208,LM308

LM108/LM208/LM308 Operational Amplifiers



Literature Number: SNOSBS5A

LM108/LM208/LM308

OBSOLETE September 22, 2011

Operational Amplifiers

General Description

The LM108 series are precision operational amplifiers having specifications a factor of ten better than FET amplifiers over a -55°C to +125°C temperature range.

The devices operate with supply voltages from $\pm 2V$ to $\pm 20V$ and have sufficient supply rejection to use unregulated supplies. Although the circuit is interchangeable with and uses the same compensation as the LM101A, an alternate compensation scheme can be used to make it particularly insensitive to power supply noise and to make supply bypass capacitors unnecessary.

The low current error of the LM108 series makes possible many designs that are not practical with conventional ampli-

fiers. In fact, it operates from 10 $M\Omega$ source resistances, introducing less error than devices like the 709 with 10 $k\Omega$ sources. Integrators with drifts less than 500 $\mu V/sec$ and analog time delays in excess of one hour can be made using capacitors no larger than 1 $\mu F.$

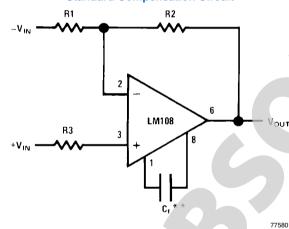
The LM108 is guaranteed from -55°C to +125°C, the LM208 from -25°C to +85°C, and the LM308 from 0°C to +70°C.

Features

- Maximum input bias current of 3.0 nA over temperature
- Offset current less than 400 pA over temperature
- Supply current of only 300 µA, even in saturation
- Guaranteed drift characteristics

Compensation Circuits

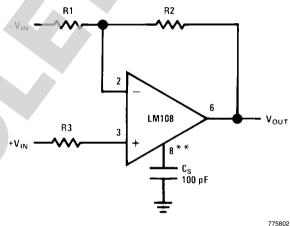
Standard Compensation Circuit



 $C_f \ge \frac{R1 C_0}{R1 + R2}$

C_O = 30 pF

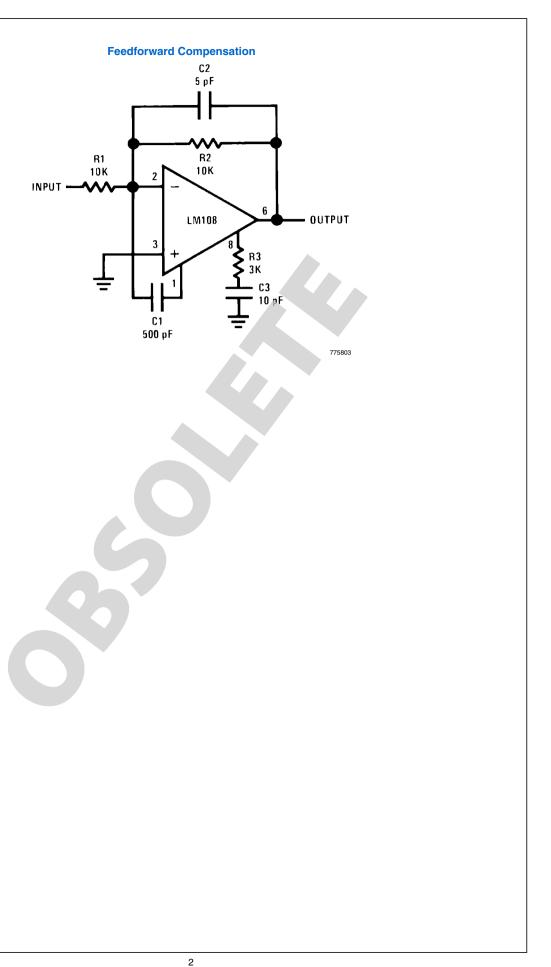
Alternate Frequency Compensation (Note 1)



**Bandwidth and slew rate are proportional to 1/Cs

Note 1: Improves rejection of power supply noise by a factor of ten.

^{**}Bandwidth and slew rate are proportional to $1/C_{\rm f}$



Absolute Maximum Ratings (Note 2)

(Note 7)

2000V

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

	LM108/LM208	LM308
Supply Voltage	±20V	±18V
Power Dissipation (Note 3)	500 mW	500 mW
Differential Input Current (Note 4)	±10 mA	±10 mA
Input Voltage (Note 5)	±15V	±15V
Output Short-Circuit Duration	Continuous	Continuous
Operating Temperature Range (LM108)	-55°C to +125°C	0°C to +70°C
(LM208)	-25°C to + 85°C	
Storage Temperature Range	−65°C to +150°C	-65°C to +150°C
Lead Temperature (Soldering, 10 sec)		
DIP	260°C	260°C
H Package Lead Temp		
(Soldering 10 seconds)	300°C	300°C
Soldering Information		
Dual-In-Line Package		
Soldering (10 seconds)	260°C	
Small Outline Package		
Vapor Phase (60 seconds)	215°C	
Infrared (15 seconds)	220°C	
See AN-450 "Surface Mounting Methods and Their Effect methods of soldering surface mount devices.	t on Product Reliability" for other	

Electrical Characteristics (Note 6)

ESD Tolerance (Note 8)

Parameter	Condition	LI	LM108/LM208			LM308		
	Condition	Min	Тур	Max	Min	Тур	Max	Units
Input Offset Voltage	T _A = 25°C		0.7	2.0		2.0	7.5	mV
Input Offset Current	T _A = 25°C		0.05	0.2		0.2	1	nA
Input Bias Current	T _A = 25°C		0.8	2.0		1.5	7	nA
Input Resistance	T _A = 25°C	30	70		10	40		МΩ
Supply Current	T _A = 25°C		0.3	0.6		0.3	0.8	mA
Large Signal Voltage	$T_A = 25^{\circ}C, V_S = \pm 15V$	50	300		25	300		V/mV
Gain	$V_{OUT} = \pm 10V$, $R_L \ge 10 \text{ k}\Omega$							
Input Offset Voltage				3.0			10	mV
Average Temperature								
Coefficient of Input			3.0	15		6.0	30	μV/°C
Offset Voltage								
Input Offset Current				0.4			1.5	nA
Average Temperature								
Coefficient of Input			0.5	2.5		2.0	10	pA/°C
Offset Current								
Input Bias Current				3.0			10	nA
Supply Current	T _A = +125°C		0.15	0.4				mA
Large Signal Voltage	$V_S = \pm 15V, V_{OUT} = \pm 10V$	25			15			V/mV
Gain	R _L ≥ 10 kΩ							
Output Voltage Swing	$V_S = \pm 15V, R_L = 10 \text{ k}\Omega$	±13	±14		±13	±14		V
Input Voltage Range	V _S = ±15V	±13.5			±14			V

Parameter	Condition	LM108/LM208			LM308			Units
		Min	Тур	Max	Min	Тур	Max	Units
Common Mode		85	100		80	100		dB
Rejection Ratio								
Supply Voltage		80	96		80	96		dB
Rejection Ratio								

Note 2: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits.

Note 3: The maximum junction temperature of the LM108 is 150°C, for the LM208, 100°C and for the LM308, 85°C. For operating at elevated temperatures, devices in the H08 package must be derated based on a thermal resistance of 160°C/W, junction to ambient, or 20°C/W, junction to case. The thermal resistance of the dual-in-line package is 100°C/W, junction to ambient.

Note 4: The inputs are shunted with back-to-back diodes for overvoltage protection. Therefore, excessive current will flow if a differential input voltage in excess of 1V is applied between the inputs unless some limiting resistance is used.

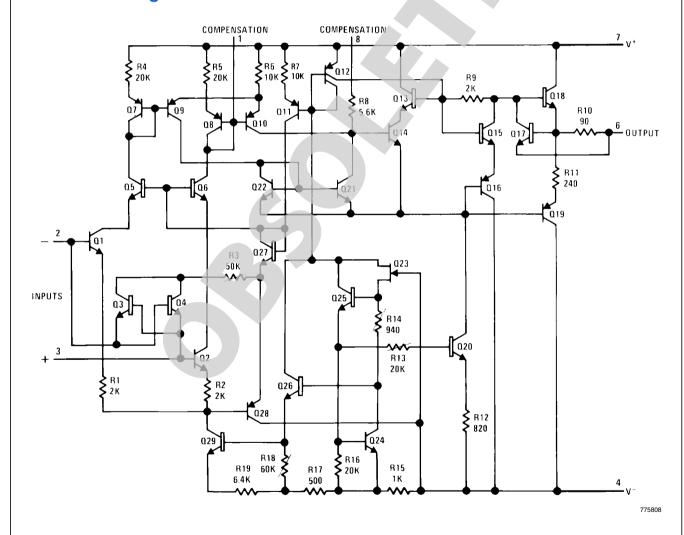
Note 5: For supply voltages less than ±15V, the absolute maximum input voltage is equal to the supply voltage.

Note 6: These specifications apply for $\pm 5\text{V} \le \text{V}_S \le \pm 20\text{V}$ and $-55^{\circ}\text{C} \le \text{T}_A \le +125^{\circ}\text{C}$, unless otherwise specified. With the LM208, however, all temperature specifications are limited to $-25^{\circ}\text{C} \le \text{T}_A \le 85^{\circ}\text{C}$, and for the LM308 they are limited to $0^{\circ}\text{C} \le \text{T}_A \le 70^{\circ}\text{C}$.

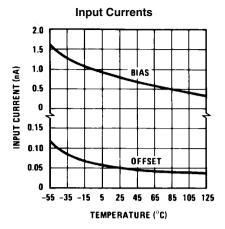
Note 7: Refer to RETS108X for LM108 military specifications and RETs 108AX for LM108A military specifications.

Note 8: Human body model, $1.5 \text{ k}\Omega$ in series with 100 pF.

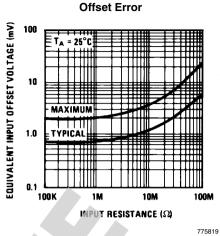
Schematic Diagram

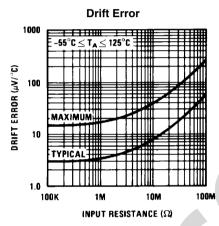


Typical Performance Characteristics LM108/LM208

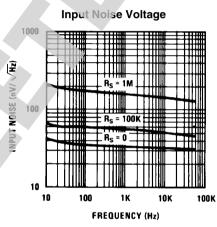


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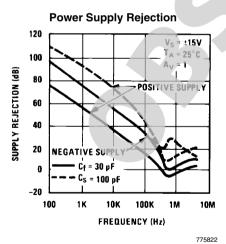




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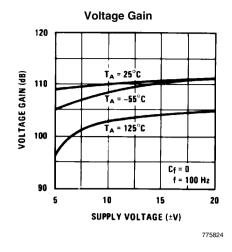


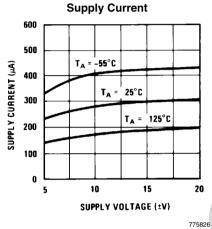
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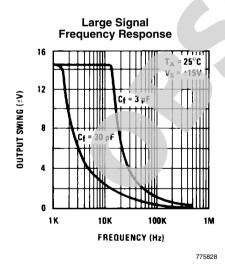


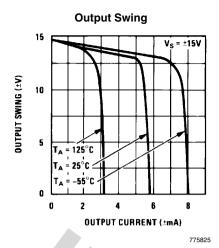
Closed Loop Output Impedance 10³ 10² OUTPUT IMPEDANCE (52) 10 Av = 1, Cf = 30 pf 10º A_V = 1000, Cf = 0 pF A_{V} = 1000, Cf = 30 pf 10-1 I_{OUT} = ±1 mA V_S = ±15V 10-2 10M 100K 1 M 10 100 1K 10K FREQUENCY (Hz)

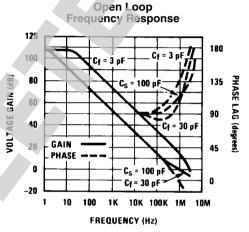
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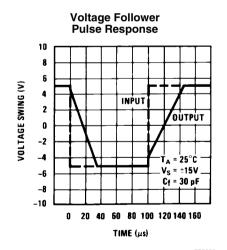






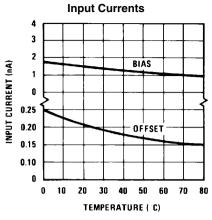


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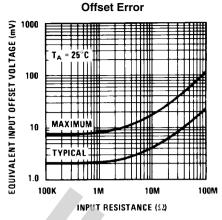


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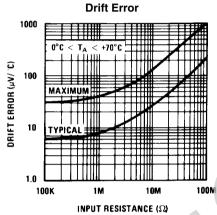
Typical Performance Characteristics LM308



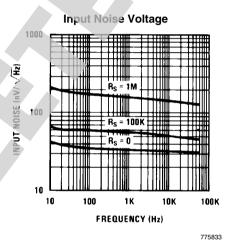
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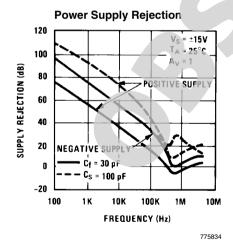


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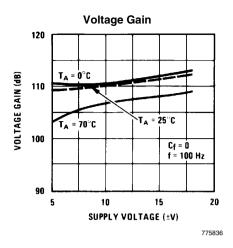
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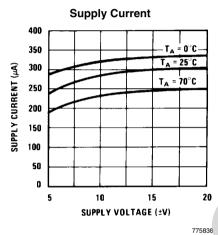


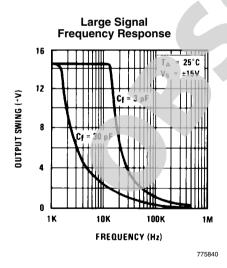


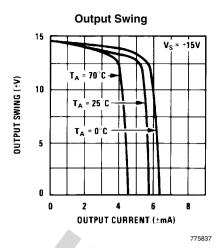
Closed Loop Output Impedance 10 10² **OUTPUT IMPEDANCE (52)** 10 $A_{V} = 1$, $C_{f} = 30 pF$ A_V = 1000, Cf = 0 pF 100 1000, Cf = 30 pf TA = 25°C 10-I_{OUT} = ±1 mA V_S = ±15V 10-2 100K 10M 10 100 10K 1M FREQUENCY (Hz)

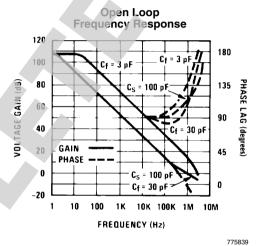
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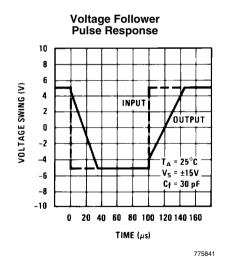


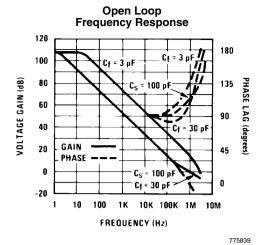


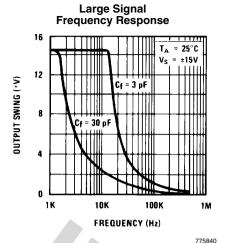


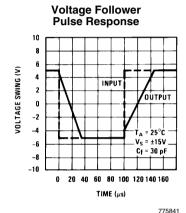






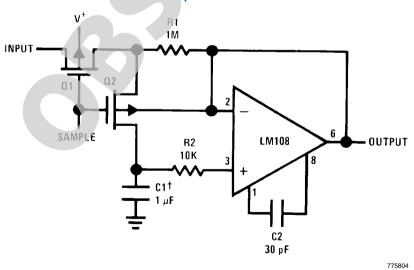






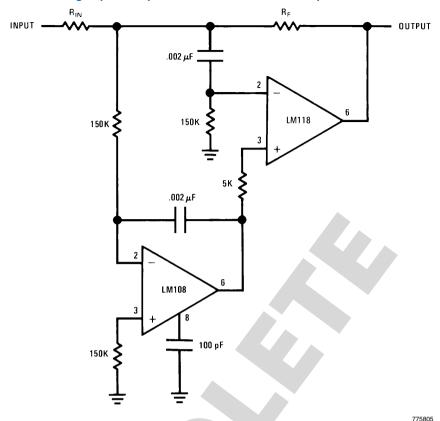
Typical Applications

Sample and Hold

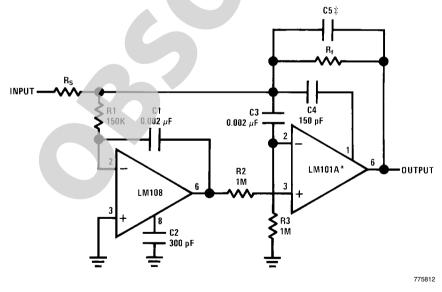


†Teflon polyethylene or polycarbonate dielectric capacitor Worst case drift less than 2.5 mV/sec

High Speed Amplifier with Low Drift and Low Input Current



Fast Summing Amplifier (Note 9)



 $\ddagger C5 = \frac{6 \times 10^{-8}}{R_f}$

*In addition to increasing speed, the LM101A raises high and low frequency gain, increases output drive capability and eliminates thermal feedback.

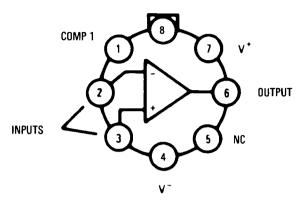
Note 9: Power Bandwidth: 250 KHz Small Signal Bandwidth: 3.5 MHz

Slew Rate: 10V/µS

10

Connection Diagrams

Metal Can Package COMP 2



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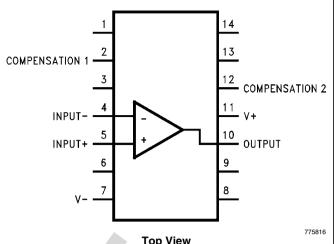
*Package is connected to Pin 4 (V-)

**Unused pin (no internal connection) to allow for input anti-leakage guard ring on printed circuit board layout.

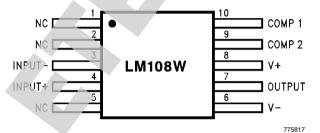
Order Number LM108H, LM108H/883, LM308AH or LM308H See NS Package Number H08C

Dual-In-Line Package COMP 1 INPUT - 2 INPUT + 3 V- 4 V- 4 Dual-In-Line Package 8 COMP 2 7 V+ 6 OUTPUT

Top View
Order Number LM108J-8/883, LM308M or LM308N
See NS Package Number J08A, M08A or N08E



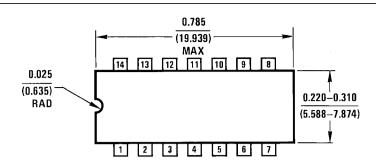
Top View Order Number LM108J/883 See NS Package Number J14A

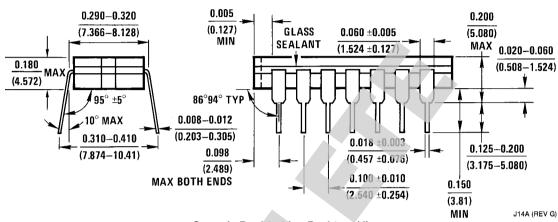


†Also available per JM38510/10104

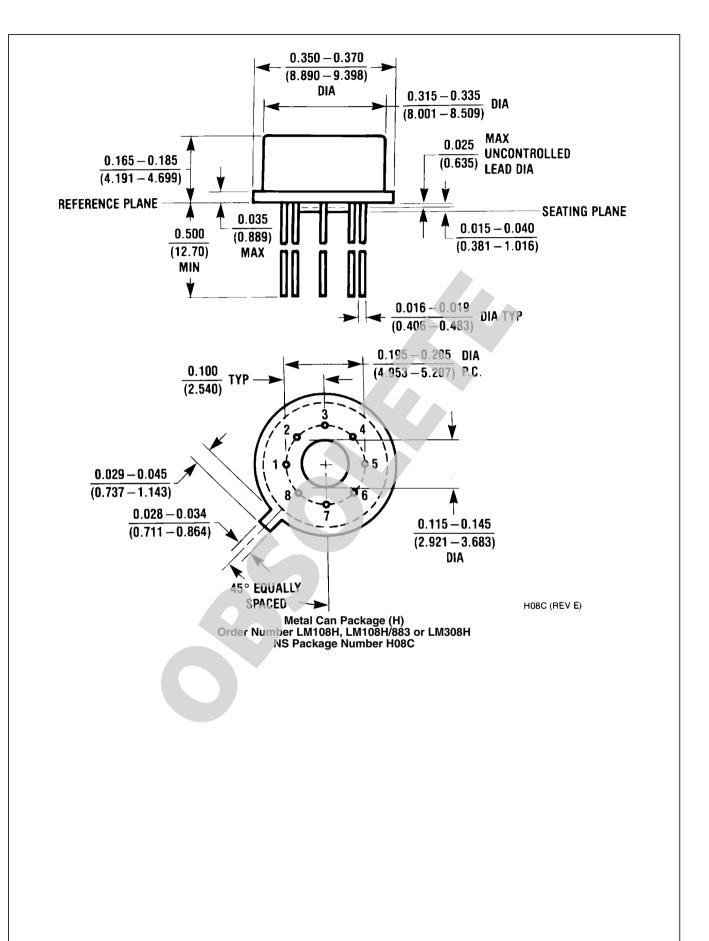
Order Number LM108W/883 See NS Package Number W10A

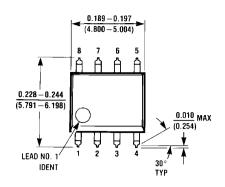
Physical Dimensions inches (millimeters) unless otherwise noted 0.400 MAX R0.010 TYP 5 7 6 0.220 0.310 MAX 0.291 GLASS R0.025 TYP-2 3 4 1 0.045 0.065 TYP 0.290 0.320 GLASS SEALANT 0.005 MIN 0.180 0.020 0.060 0.200 MAX MAX ↑ 0.150 0.125 MIN 0.200 90° ± 4° TYP 95° ± 5° TYP 0.055 MAX 0.310 BOTH ENDS 0.410 0.008 0.012 TYP 0.018 ± 0.003 TYP 0.100 ± 0.010 TYP JOSA (REV K) Ceramic Dual-In-Line Package (J) Order Number LM108J/883 NS Package Number J08A

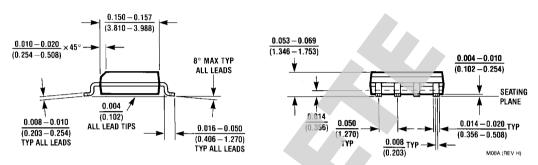




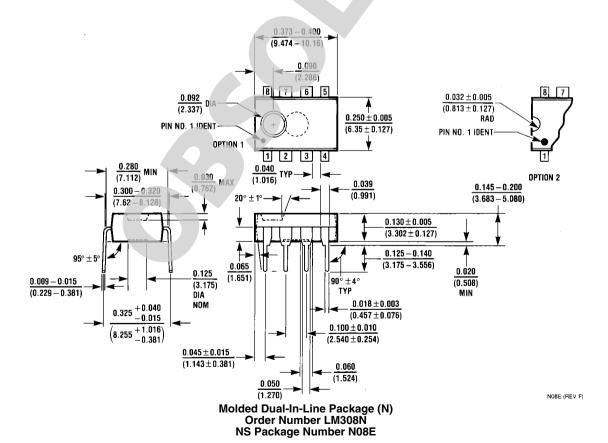
Ceramic Dual-In-Line Package (J) Order Number LM108/883 NS Package Number J14A

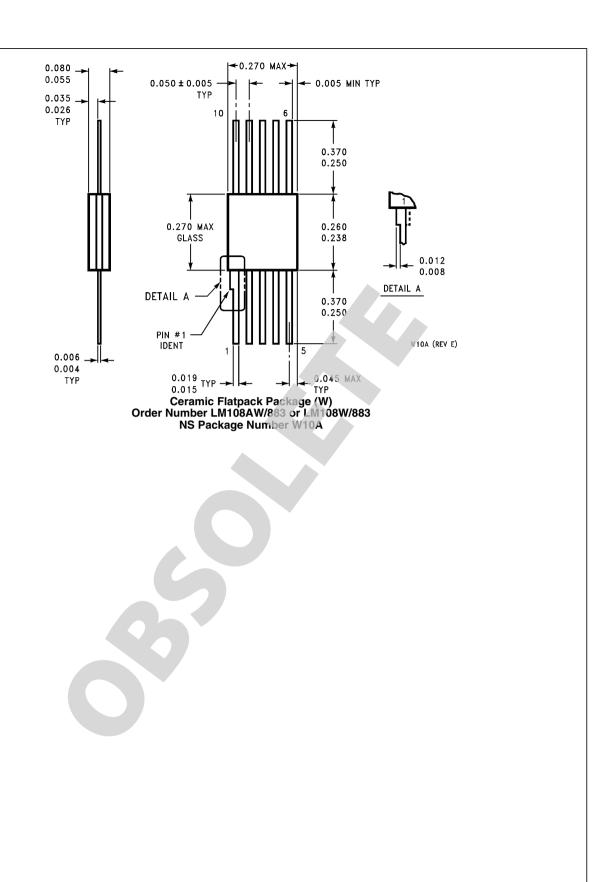


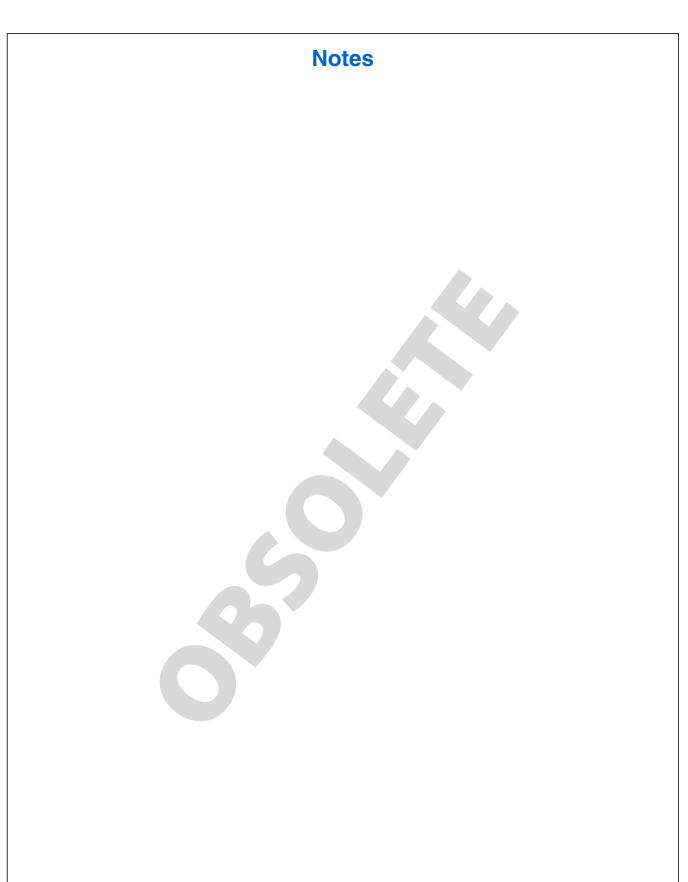




S.O. Package (M) Order Number LM308M NS Package Number M08A







Notes

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